ASMI ANNUAL MEETING OF SHAREHOLDERS

Chuck del Prado, President & CEO
May 16 2013
SAFE HARBOR STATEMENTS

Safe Harbor Statement under the U.S. Private Securities Litigation Reform Act of 1995: All matters discussed in this business and strategy update, except for any historical data, are forward-looking statements. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. These include, but are not limited to, economic conditions and trends in the semiconductor industry generally and the timing of the industry cycles specifically, currency fluctuations, corporate transactions, financing and liquidity matters, the success of restructurings, the timing of significant orders, market acceptance of new products, competitive factors, litigation involving intellectual property, shareholder and other issues, commercial and economic disruption due to natural disasters, terrorist activity, armed conflict or political instability, epidemics and other risks indicated in the Company's filings from time to time with the U.S. Securities and Exchange Commission, including, but not limited to, the Company's reports on Form 20-F and Form 6-K. The company assumes no obligation to update or revise any forward-looking statements to reflect future developments or circumstances.
Semiconductor Equipment Market in 2012
ASMI Results in 2012
Status ASMI Back-end
  - Results
  - Products & Business highlights
Status ASMI Front-end
  - Results
  - Products & Business highlights
Market Outlook and Conclusions
OUR INDUSTRY TURNED DOWN IN 2012

Semi Capital Equipment
(USD billion)

After 2 years of growth, our industry declined in 2012

Source: Gartner, March 2013
Assembly & Packaging equipment market 2012
(USD billion)

Assembly & Packaging equipment spending declined in 2012

Source: Gartner, March 2013
SMT equipment market 2012
(USD million)

SMT equipment market was down in 2012

Source: ASM SIPLACE market intelligence, February 2013

*SMT = Surface Mount Technology
Wafer Fab Equipment by device type
(USD billion)

- 2012 WFE spending decreased by 18%
- Logic & Foundry declined slightly in 2012
- Memory declined substantially

Source: Gartner, March 2013
OUTLINE

» Semiconductor Equipment Market in 2012
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» Market Outlook and Conclusions
KEY HIGHLIGHTS – 2012

› **Revenues down 13% y-o-y**
  - FE sales decreased 19% y-o-y
  - BE sales decreased 11% y-o-y

› **EBIT margin of 6%**
  - FE EBIT margin down from 14% in 2011 to 0.4% in 2012
  - BE EBIT margin down from 18% in 2011 to 8% in 2012

› **Cash flow from operations of €42m in 2012**
  - Proposal to ASMI AGM for dividend of €0.50 per share

› **Net earnings of €7m down from €187m in 2011**
  - 2011 included gain on bargain purchase of €51m
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<thead>
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<th></th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>NET EARNINGS</strong></td>
<td></td>
<td></td>
<td></td>
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<td></td>
</tr>
<tr>
<td><strong>GROUP</strong></td>
<td></td>
<td></td>
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<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Front-end</td>
<td>456.1</td>
<td>370.4</td>
<td>94.8</td>
<td>86.5</td>
<td>96.1</td>
<td>93.1</td>
<td>80.0</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Back-end</td>
<td>1,178.3</td>
<td>1,047.7</td>
<td>216.3</td>
<td>291.4</td>
<td>313.2</td>
<td>226.8</td>
<td>160.3</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>NET SALES</strong></td>
<td>1,634.3</td>
<td>1,418.1</td>
<td>311.1</td>
<td>377.9</td>
<td>409.3</td>
<td>319.9</td>
<td>240.3</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Front-end</td>
<td>37.8%</td>
<td>33.6%</td>
<td>33.0%</td>
<td>33.0%</td>
<td>31.4%</td>
<td>37.1%</td>
<td>37.7%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Back-end</td>
<td>34.8%</td>
<td>30.2%</td>
<td>30.2%</td>
<td>35.0%</td>
<td>30.4%</td>
<td>23.5%</td>
<td>24.0%</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>GROSS MARGIN</strong></td>
<td>582.2</td>
<td>440.4</td>
<td>96.6</td>
<td>130.6</td>
<td>125.4</td>
<td>87.8</td>
<td>68.6</td>
<td></td>
<td></td>
</tr>
<tr>
<td>as % of sales</td>
<td>35.6%</td>
<td>31.1%</td>
<td>31.1%</td>
<td>34.6%</td>
<td>30.6%</td>
<td>27.4%</td>
<td>28.5%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Selling, general and administrative</td>
<td>(176.5)</td>
<td>(202.1)</td>
<td>(41.2)</td>
<td>(53.8)</td>
<td>(53.6)</td>
<td>(53.5)</td>
<td>(40.9)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Research and development</td>
<td>(129.4)</td>
<td>(149.2)</td>
<td>(33.5)</td>
<td>(38.2)</td>
<td>(40.0)</td>
<td>(37.5)</td>
<td>(30.5)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Front-end</td>
<td>62.6</td>
<td>1.4</td>
<td>2.9</td>
<td>(1.9)</td>
<td>(1.6)</td>
<td>2.1</td>
<td>1.4</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Back-end (100%)</td>
<td>213.7</td>
<td>87.7</td>
<td>19.0</td>
<td>40.5</td>
<td>33.6</td>
<td>(5.3)</td>
<td>(4.3)</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>EBIT (excl. restructuring/impairment)</strong></td>
<td>276.3</td>
<td>89.2</td>
<td>21.9</td>
<td>38.5</td>
<td>31.9</td>
<td>(3.2)</td>
<td>(2.9)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>as % of sales</td>
<td>16.9%</td>
<td>6.3%</td>
<td>7.1%</td>
<td>10.2%</td>
<td>7.8%</td>
<td>-1.0%</td>
<td>-1.2%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Restructuring</td>
<td>-</td>
<td>(0.9)</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>(0.9)</td>
<td>(0.3)</td>
<td></td>
</tr>
<tr>
<td>Bargain purchase (PPA)</td>
<td>97.8</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Impairment</td>
<td>(8.0)</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Front-end</td>
<td>44.5</td>
<td>(29.1)</td>
<td>(2.5)</td>
<td>1.3</td>
<td>(8.4)</td>
<td>(19.5)</td>
<td>3.1</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Back-end (ASMI interest)</td>
<td>142.2</td>
<td>36.4</td>
<td>8.8</td>
<td>16.5</td>
<td>13.3</td>
<td>(2.2)</td>
<td>(0.5)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gain on sale shares</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>1,407.6</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>NET RESULT</strong></td>
<td>186.8</td>
<td>7.1</td>
<td>6.2</td>
<td>17.7</td>
<td>4.9</td>
<td>(21.7)</td>
<td>1,410.1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
# BALANCE SHEET – GROUP

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash and cash equivalents</td>
<td>390</td>
<td>405</td>
<td>334</td>
<td>297</td>
<td>291</td>
<td>565</td>
</tr>
<tr>
<td>Other current assets</td>
<td>806</td>
<td>773</td>
<td>917</td>
<td>901</td>
<td>804</td>
<td>208</td>
</tr>
<tr>
<td>Property, plant and equipment, net</td>
<td>260</td>
<td>259</td>
<td>279</td>
<td>275</td>
<td>275</td>
<td>61</td>
</tr>
<tr>
<td>Goodwill, net</td>
<td>52</td>
<td>51</td>
<td>54</td>
<td>52</td>
<td>52</td>
<td>12</td>
</tr>
<tr>
<td>Other assets</td>
<td>74</td>
<td>74</td>
<td>84</td>
<td>89</td>
<td>75</td>
<td>1,381</td>
</tr>
<tr>
<td><strong>TOTAL ASSETS</strong></td>
<td><strong>1,582</strong></td>
<td><strong>1,561</strong></td>
<td><strong>1,668</strong></td>
<td><strong>1,615</strong></td>
<td><strong>1,496</strong></td>
<td><strong>2,226</strong></td>
</tr>
<tr>
<td>ST debt (incl. current LT debt)</td>
<td>45</td>
<td>40</td>
<td>72</td>
<td>86</td>
<td>68</td>
<td>-</td>
</tr>
<tr>
<td>Other current liabilities</td>
<td>418</td>
<td>409</td>
<td>449</td>
<td>390</td>
<td>344</td>
<td>86</td>
</tr>
<tr>
<td>Long-term debt &amp; convertible subordinated debt</td>
<td>150</td>
<td>150</td>
<td>152</td>
<td>144</td>
<td>13</td>
<td>-</td>
</tr>
<tr>
<td>Other long term liabilities</td>
<td>11</td>
<td>11</td>
<td>17</td>
<td>17</td>
<td>21</td>
<td>4</td>
</tr>
<tr>
<td><strong>TOTAL LIABILITIES</strong></td>
<td><strong>625</strong></td>
<td><strong>610</strong></td>
<td><strong>690</strong></td>
<td><strong>637</strong></td>
<td><strong>446</strong></td>
<td><strong>90</strong></td>
</tr>
<tr>
<td>Total shareholders’ equity</td>
<td>660</td>
<td>653</td>
<td>665</td>
<td>667</td>
<td>742</td>
<td>2,136</td>
</tr>
<tr>
<td>Non-controlling interest</td>
<td>298</td>
<td>298</td>
<td>313</td>
<td>311</td>
<td>308</td>
<td>-</td>
</tr>
<tr>
<td><strong>TOTAL LIABILITIES AND EQUITY</strong></td>
<td><strong>1,582</strong></td>
<td><strong>1,561</strong></td>
<td><strong>1,668</strong></td>
<td><strong>1,615</strong></td>
<td><strong>1,496</strong></td>
<td><strong>2,226</strong></td>
</tr>
</tbody>
</table>
# CASH FLOW – GROUP

<table>
<thead>
<tr>
<th>(EUR million)</th>
<th>FULL YEAR 2011</th>
<th>FULL YEAR 2012</th>
<th>Q1 2012</th>
<th>Q2 2012</th>
<th>Q3 2012</th>
<th>Q4 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net result</td>
<td>316.2</td>
<td>40.4</td>
<td>14.2</td>
<td>32.8</td>
<td>17.2</td>
<td>(23.8)</td>
</tr>
<tr>
<td>Depreciation</td>
<td>49.5</td>
<td>56.9</td>
<td>13.1</td>
<td>13.7</td>
<td>15.1</td>
<td>15.0</td>
</tr>
<tr>
<td>Working capital</td>
<td>(39.2)</td>
<td>(60.8)</td>
<td>19.3</td>
<td>(62.2)</td>
<td>(59.7)</td>
<td>41.8</td>
</tr>
<tr>
<td>Restructuring &amp; impairments</td>
<td>4.9</td>
<td>0.1</td>
<td>0.1</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>Others</td>
<td>(114.7)</td>
<td>5.9</td>
<td>(7.3)</td>
<td>(11.6)</td>
<td>7.7</td>
<td>17.1</td>
</tr>
<tr>
<td><strong>Net cash from operating activities</strong></td>
<td><strong>216.6</strong></td>
<td><strong>42.5</strong></td>
<td><strong>40.2</strong></td>
<td><strong>(27.2)</strong></td>
<td><strong>(19.8)</strong></td>
<td><strong>50.1</strong></td>
</tr>
<tr>
<td>Net cash from investing activities</td>
<td><strong>(93.4)</strong></td>
<td><strong>(71.9)</strong></td>
<td><strong>(18.4)</strong></td>
<td><strong>(17.8)</strong></td>
<td><strong>(14.5)</strong></td>
<td><strong>(21.1)</strong></td>
</tr>
<tr>
<td>Net cash from financing activities</td>
<td><strong>(45.4)</strong></td>
<td><strong>(73.5)</strong></td>
<td><strong>(5.8)</strong></td>
<td><strong>(27.4)</strong></td>
<td><strong>(5.2)</strong></td>
<td><strong>(35.1)</strong></td>
</tr>
<tr>
<td>Exchange rate effects</td>
<td><strong>(7.8)</strong></td>
<td><strong>3.1</strong></td>
<td><strong>(0.8)</strong></td>
<td><strong>1.5</strong></td>
<td><strong>3.2</strong></td>
<td><strong>(0.8)</strong></td>
</tr>
<tr>
<td><strong>NET INCREASE (DECREASE) IN CASH AND CASH EQUIVALENTS</strong></td>
<td><strong>70.0</strong></td>
<td><strong>(99.8)</strong></td>
<td><strong>14.4</strong></td>
<td><strong>(70.9)</strong></td>
<td><strong>(36.4)</strong></td>
<td><strong>(6.8)</strong></td>
</tr>
</tbody>
</table>
**Bookings** (EUR million)

Book to bill ratio in 2012 of 1.0 (2011 was 0.8)

**Backlog** (EUR million)

Backlog decreased from €331m at the end of 2011, to €289m at the end of 2012
# USE OF ASMPT DIVIDENDS

<table>
<thead>
<tr>
<th>(EUR million)</th>
<th>Dividends received</th>
<th>ASMI shares repurchased</th>
<th>Convertible bonds repurchased</th>
<th>Dividend pay outs</th>
<th>Balance</th>
</tr>
</thead>
<tbody>
<tr>
<td>2007</td>
<td>49.1</td>
<td></td>
<td>-32.9</td>
<td>-5.4</td>
<td>10.8</td>
</tr>
<tr>
<td>2008</td>
<td>49.1</td>
<td>-36.5</td>
<td>-27.1</td>
<td></td>
<td>-14.5</td>
</tr>
<tr>
<td>2009</td>
<td>21.4</td>
<td></td>
<td>-27.0</td>
<td></td>
<td>-5.6</td>
</tr>
<tr>
<td>2010</td>
<td>65.6</td>
<td></td>
<td>-55.8</td>
<td></td>
<td>9.8</td>
</tr>
<tr>
<td>2011</td>
<td>87.2</td>
<td></td>
<td></td>
<td>-22.3</td>
<td>64.9</td>
</tr>
<tr>
<td><strong>2012</strong></td>
<td>*</td>
<td>-40.6</td>
<td></td>
<td>-27.5</td>
<td>-68.1</td>
</tr>
<tr>
<td><strong>TOTAL</strong></td>
<td><strong>272.4</strong></td>
<td><strong>-77.1</strong></td>
<td><strong>-142.8</strong></td>
<td><strong>-55.2</strong></td>
<td><strong>-2.7</strong></td>
</tr>
</tbody>
</table>

*2012 PT dividend received of 29.5 was not part of commitment*

1.5 million shares bought back in 2012
ASMI SHARE PRICE IN 2012

- ASMI share price increased 20% in 2012, but declined in March’13 following sale stake ASMPT
- Comparison same sector companies

Source: google.com/finance and Euronext
ASMI SHARE PRICE LAST 5 YEARS

ASMI share price increased 49% (end of 2012) compared to 2008

Source: google.com/finance and Euronext
COMMITMENT TO SUSTAINABILITY

We are committed to the Electronics Industry Citizenship Coalition (EICC) tenets to conduct our business responsibly in all areas of Environment, Health & Safety, Labor, Ethics and Supply Chain.

We strive to earn the trust of all stakeholders through responsible and ethical corporate practices.

In both our Front-end and Back-end businesses, we pride ourselves in being responsible corporate citizens.

Front-end

- Sustainability policy published 2/13
- Internal EICC audit all sites completed 1/13
- External EICC re-audit of Singapore site 5/13 successful, zero open findings
- Annual ethics training completed 10/12
- Ethics Scorecard in place 4/13

Back-end

- CSR Policy draft in review, target Q2-13
- 3rd party EICC audit of HK and China complete 7/12, corrective actions underway
- EICC self-assessment done for 5 of 8 facilities, rest complete by Q3-13
- Ethics training all employees annually

Transparency ➔ ASM Internet site - Sustainability
HEALTH, SAFETY, ENVIRONMENT

**Front-end**
- Among benchmark companies
- Key customer recognition for EHS

**Back-end**
- RCR continues to outperform Industry
- Safety Training top-to-bottom improvement
- Risk Assessment and risk-focused actions

### Recordable Case Rate (CY)

![Recordable Case Rate Graph]

**Front-end**
- Global ISO14001 by 7/13
- Environmental Scorecard 1/13
- Carbon Disclosure Project (CDP) participation 5/13

**Back-end**
- 5 of 8 facilities ISO14001 certified now
- Global ISO14001 target by 2016 end
- Environmental Scorecard in place
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BACK-END – WHAT HAS CHANGED IN 2012?

› Assembly & Packaging revenue down 23% compared to 2011

› Record leadframe revenue, leadframe business profitable

› SMT improved its market position and profit margin in 2012
<table>
<thead>
<tr>
<th></th>
<th>FULL YEAR 2011</th>
<th>FULL YEAR 2012</th>
<th>Q1 2012</th>
<th>Q2 2012</th>
<th>Q3 2012</th>
<th>Q4 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net sales</td>
<td>1,178.3</td>
<td>1,047.7</td>
<td>216.3</td>
<td>291.4</td>
<td>313.2</td>
<td>226.8</td>
</tr>
<tr>
<td>Gross margin</td>
<td>409.8</td>
<td>315.9</td>
<td>65.3</td>
<td>102.0</td>
<td>95.3</td>
<td>53.3</td>
</tr>
<tr>
<td>as % of sales</td>
<td>34.8%</td>
<td>30.2%</td>
<td>30.2%</td>
<td>35.0%</td>
<td>30.4%</td>
<td>23.5%</td>
</tr>
<tr>
<td>Selling, general and administrative</td>
<td>(115.3)</td>
<td>(137.6)</td>
<td>(26.6)</td>
<td>(38.5)</td>
<td>(37.2)</td>
<td>(35.4)</td>
</tr>
<tr>
<td>Research &amp; development</td>
<td>(80.9)</td>
<td>(90.5)</td>
<td>(19.7)</td>
<td>(23.1)</td>
<td>(24.5)</td>
<td>(23.2)</td>
</tr>
<tr>
<td>EBIT (EXCL. IMPAIRMENT)</td>
<td>213.7</td>
<td>87.7</td>
<td>19.0</td>
<td>40.5</td>
<td>33.6</td>
<td>(5.3)</td>
</tr>
<tr>
<td>as % of sales</td>
<td>18.1%</td>
<td>8.4%</td>
<td>8.8%</td>
<td>13.9%</td>
<td>10.7%</td>
<td>-2.3%</td>
</tr>
<tr>
<td>Bookings</td>
<td>971</td>
<td>1,017</td>
<td>282</td>
<td>334</td>
<td>210</td>
<td>191</td>
</tr>
<tr>
<td>BOOK-TO-BILL</td>
<td>0.8</td>
<td>1.0</td>
<td>1.3</td>
<td>1.1</td>
<td>0.7</td>
<td>0.8</td>
</tr>
</tbody>
</table>
**Bookings** (EUR million)

- Book-to-Bill ratio in 2012 was 1.0

**Backlog** (EUR million)

- Backlog declined 12% to €198m in 2012
IC manufacturing - LED manufacturing - Surface Mount Technology

MARKET

IC manufacturing
- Assembly tools
- Packaging tools
- Inspection tools

LED manufacturing
- Assembly tools
- Packaging tools
- Testing tools

SMT
- Placement tools

APPLICATION

IC manufacturing
- Die bonding
- Wire bonding
- Flip chip bonding / TCB bonding
- Moulding
- Trim & Form
- Vision and Inspection

LED manufacturing
- Die bonding
- Wire bonding
- Moulding
- Trim & Form
- Vision and Inspection
- Sorting
- Testing

SMT
- Pick & Place
- Automation software

ASM RELATIVE POSITIONING

IC manufacturing
- Among the top 2 position for most products
- Qualified by most IDM’s and Subcontractors’
- Strong local service and support organization
- Total solution selling

LED manufacturing
- #1 in the bonding market
- Complete manufacturing tools portfolio
- Entered LED market already in 2006
- Strong local service and support organization

SMT
- ASM #3 vendor
- Leading position in High-end tools
Capable to address fine pitch flip chip (Cu pillar) bonding and 2.5D/3D package applications

Popularity of mobile devices expected to accelerate adoption of 2.5D/3D packages
Chip Assembly (CA) solution for advanced packages

- Expanding SMT equipment into non-traditional placement market
- Ideal for WLFO (Wafer Level Fan Out), SiP (System-in-package), LED, Embedded PCB and flip chips
- Enables the combination of flip-chip and SMT operations in a single pass
- Supports direct die attach
- Supports large panel areas
- Very high production speed and throughput
OUTLINE

› Semiconductor Equipment Market in 2012
› ASMI Results in 2012
› Status ASMI Back-end
   - Results
   - Products & Business highlights
› Status ASMI Front-end
   - Results
   - Products & Business highlights
› Market Outlook and Conclusions
HISTORICAL DEVELOPMENT – FRONT-END

Net sales in EUR million

EBIT in EUR million

Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1
07 08 09 10 11 12 13
### SUMMARY 2012 – FRONT-END

<table>
<thead>
<tr>
<th>(EUR million)</th>
<th>Full Year 2011</th>
<th>Full Year 2012</th>
<th>Q1 2012</th>
<th>Q2 2012</th>
<th>Q3 2012</th>
<th>Q4 2012</th>
<th>Q1 2013</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net sales</td>
<td>456.1</td>
<td>370.4</td>
<td>94.8</td>
<td>86.5</td>
<td>96.1</td>
<td>93.1</td>
<td>80.0</td>
</tr>
<tr>
<td>Gross margin</td>
<td>172.3</td>
<td>124.5</td>
<td>31.3</td>
<td>28.5</td>
<td>30.1</td>
<td>34.6</td>
<td>30.2</td>
</tr>
<tr>
<td>as % of sales</td>
<td>37.8%</td>
<td>33.6%</td>
<td>33.0%</td>
<td>32.9%</td>
<td>31.4%</td>
<td>37.1%</td>
<td>37.7%</td>
</tr>
<tr>
<td>Selling, general and administrative</td>
<td>(61.2)</td>
<td>(64.4)</td>
<td>(14.6)</td>
<td>(15.4)</td>
<td>(16.3)</td>
<td>(18.2)</td>
<td>(15.3)</td>
</tr>
<tr>
<td>Research &amp; development</td>
<td>(48.5)</td>
<td>(58.7)</td>
<td>(13.8)</td>
<td>(15.1)</td>
<td>(15.4)</td>
<td>(14.3)</td>
<td>(13.4)</td>
</tr>
<tr>
<td>EBIT (excl. restructuring)</td>
<td>62.6</td>
<td>1.4</td>
<td>2.9</td>
<td>(1.9)</td>
<td>(1.6)</td>
<td>2.1</td>
<td>1.4</td>
</tr>
<tr>
<td>as % of sales</td>
<td>13.7%</td>
<td>0.4%</td>
<td>3.0%</td>
<td>-2.2%</td>
<td>-1.7%</td>
<td>2.3%</td>
<td>1.8%</td>
</tr>
<tr>
<td>Bookings</td>
<td>398</td>
<td>360</td>
<td>81</td>
<td>86</td>
<td>64</td>
<td>129</td>
<td>106</td>
</tr>
<tr>
<td>Book-to-Bill</td>
<td>0.9</td>
<td>1.0</td>
<td>0.8</td>
<td>1.0</td>
<td>0.7</td>
<td>1.4</td>
<td>1.3</td>
</tr>
</tbody>
</table>
Bookings & Backlog – Front-end

Book-to-Bill ratio in 2012 of 1.0
Market requirements: 32nm → 22nm → 14nm and beyond

Strong IP protected portfolio

<table>
<thead>
<tr>
<th>PROCESS</th>
<th>APPLICATION</th>
<th>ASM RELATIVE POSITIONING</th>
</tr>
</thead>
<tbody>
<tr>
<td>ALD and PEALD</td>
<td>• ALD key for High-k Metal Gate technology</td>
<td>✓ #1 in the served ALD market</td>
</tr>
<tr>
<td></td>
<td>• 3D FinFET requires more conformal layers, strength of ALD</td>
<td>✓ Qualified by nearly all Logic &amp; Foundry manufacturers</td>
</tr>
<tr>
<td></td>
<td>• SDDP-application of PEALD</td>
<td>✓ Strengthening inroads with PEALD</td>
</tr>
<tr>
<td></td>
<td>› ALD solution (Hafnium oxide)</td>
<td></td>
</tr>
<tr>
<td></td>
<td>› PEALD Low temp dielectrics</td>
<td></td>
</tr>
<tr>
<td>Diffusion Furnace</td>
<td>• Smallest footprint per reactor</td>
<td>✓ Leading IC manufacturers are customers</td>
</tr>
<tr>
<td></td>
<td>• Low Cost of Ownership</td>
<td></td>
</tr>
<tr>
<td>Epitaxy</td>
<td>› Epitaxial films for both analog devices as well as NMOS/PMOS</td>
<td>✓ ASM one of only two top vendors</td>
</tr>
<tr>
<td></td>
<td>• Thick Epi layers for power devices</td>
<td></td>
</tr>
<tr>
<td></td>
<td>• Strained Epi films for CMOS</td>
<td></td>
</tr>
<tr>
<td>PECVD</td>
<td>› Extreme low-k films</td>
<td>✓ ASM one of only two top vendors in PE-CVD Low-k</td>
</tr>
</tbody>
</table>
FRONT-END – WHAT HAS CHANGED IN 2012? (I)

› ALD and PEALD strongly developed further traction in 2012

› Growing share of wallet with top clients

› Two new high productivity platforms introduced in 2012

› Gross margin improvement focus
  - Inefficiency issues solved
  - Several cost measures in implementation
  - Further savings opportunities identified in supply chain
Two new high productivity platforms

Intrepid™ XP
Epitaxy

High productivity XP cluster with 4 Epi reactors

Two new high productivity platforms

High throughput, low CoO single wafer deposition tool
Key Developments:

› Diversification of customer base from Logic to Memory and Foundries
› Weight of Asia growing
› Wider adoption number of top capex customers

Customer Revenue (%)

<table>
<thead>
<tr>
<th>Year</th>
<th>Top 3</th>
<th>Nr 4-10</th>
<th>Rest</th>
</tr>
</thead>
<tbody>
<tr>
<td>2009</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>2010</td>
<td></td>
<td></td>
<td></td>
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<tr>
<td>2011</td>
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<td></td>
</tr>
<tr>
<td>2012</td>
<td></td>
<td></td>
<td></td>
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<tr>
<td>2013E</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
FRONT-END’S COMPETITIVE ADVANTAGES

- Established a leading position in ALD technology, since start in 1999
- Shift from Planar Logic to 3D FinFET will require more ALD/PEALD
- PEALD offered on high productivity platform
- ASMI is one of the two leading suppliers of PECVD Low-k films
- In the EPI market ASMI is one of only two global suppliers
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Semi capital equipment outlook (USD billion)

Market predicted to be down in 2013 by approximately 8% and to grow in 2014

Source: Gartner, March 2013
Semiconductor Sales\(^1\) ($B)

- Ultramobile PC
- Notebook PC
- Desk-based PC
- Utility/Basic Media Tablet
- Premium Media Tablet
- Premium Smartphone
- Utility/Basic Smartphone
- Traditional Mobile Phone

Semiconductor Dollars Per Unit\(^1\) ($)

- PC
- Media Tablet
- Smartphone
- Traditional Phone

1 - excludes SSD / ODD / RDD / Ethernet / graphics cards

Source: Gartner (March 2013)
Assembly & Packaging equipment spending is expected to decline in 2013, and to rebound in 2014

Source: Gartner, March 2013
Wafer Fab Equipment Forecast by technology node (USD billion)

Market Forecast shows growth in advanced technology nodes

Source: Gartner, March 2013
Based upon the current backlog and our current visibility:

- Following the healthy book to bill ratios in Q4 2012 and Q1 2013 our Front-end operations are expected to show a strong double digit sales increase in Q2 compared to Q1.

We also expect a double digit increase of our order-intake in Q2 compared to Q1.
SUMMARY

› Front-end revenue declined 19% compared to 2011

› Back-end revenue declined 11% compared to 2011

› ALD and PEALD strongly developed further traction in 2012

› Continued focus on Front-end Gross Margin improvement

› Company believes to be well positioned to benefit from the semi industry end product growth drivers in 2013-2017

› Technology shift in the industry will require more ALD/PEALD

› Front-end equipment market believed to turn around in 2013 versus weak 2012